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RECORDATIC
PATE

To the Director of the U.S. Patent and Trademark Office:

1. Name of conveying party(ies):
Jaroslav Hynecek

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): December 3, 2007

- Assignment Merger Change of Name
- Security Agreement Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other _____

2. Name and address of receiving party(ies)

Name: MagnaChip Semiconductor, Ltd.

Internal Address: _____

Street Address: _____

1 Hyangjeong-dong
Heungduk-gu, Cheongju-si

City: Chungcheongbuk-do

State: _____

Country: Republic of Korea Zip: 361-725

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

This application

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Collin W. Park
MORGAN LEWIS & BOCKIUS LLP

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6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number 50-0310
Authorized User Name Collin W. Park

9. Signature:

Collin W. Park
Signature

December 20, 2007
Date

Collin W. Park - 43,378
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents 2

ASSIGNMENT

WHEREAS I/We, the below named inventor(s) [hereinafter referred to as Assignor(s)], have made an invention entitled:

SMALL SIZE, HIGH GAIN, AND LOW NOISE PIXEL FOR CMOS IMAGE SENSORS

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Serial No. _____); and

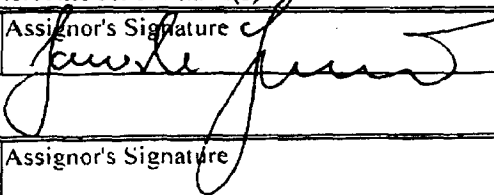
WHEREAS, MagnaChip Semiconductor Ltd., a corporation of Republic of Korea, whose post office address is 1 Hyangjeong-dong, Heungduk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____, filed Dec. 20, 2007) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Jaroslav Hynecek	Assignor's Signature 	Date 12/3/07
Address: 905 Pampa Drive, Allen, TX 75013, USA		Citizenship U.S.
Full Name of Second Assignor	Assignor's Signature	Date
Address:		Citizenship
Full Name of Third Assignor	Assignor's Signature	Date
Address:		Citizenship
Full Name of Fourth Assignor	Assignor's Signature	Date
Address:		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		

Morgan, Lewis & Bockius LLP